www.amkor.com

Taiwan Fact Sheet

Since 2001, Amkor has provided semiconductor companies and IC design houses in Taiwan with a broad range of packaging and test capabilities. Our factories are located near Hsin Chu Science Park offering easy access to foundries and customers. All of our factories meet the highest quality standards, including ISO 9001:2000, ISO14001:1996, and QS-9000:1998 certifications.

We offer industry-leading 200mm and 300mm electroplated wafer bumping, a broad portfolio of leadframe, laminate and wafer level packaging, plus turnkey solutions for flip chip, including wafer bump, probe, assembly and final test.

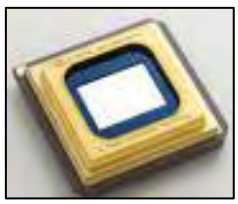
Hu Kuo (2 Factories)

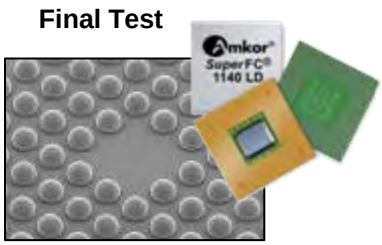
Laminate Packaging

Final Test

Turnkey Flip Chip Solutions

- **Wafer Bump – 8" & 12"**
- **CSP^{nl} – 8" & 12"**
- **Wafer Probe**
- **WLCSP**
- **Flip Chip Assembly**
- **Final Test**





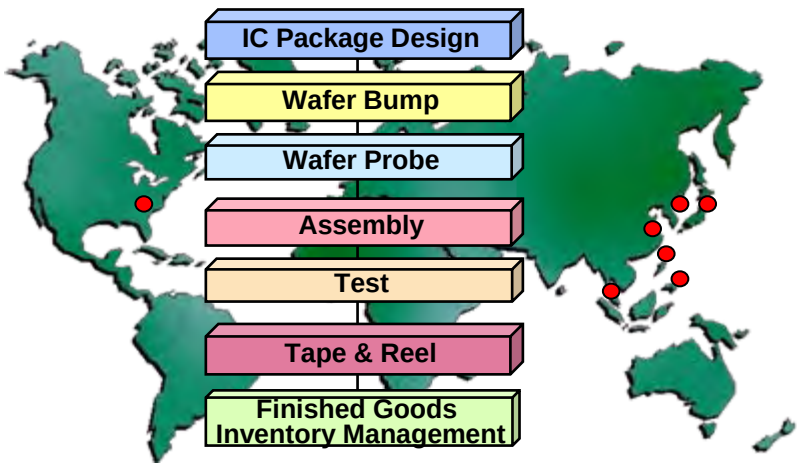
Lung Tan

Leadframe and specialty packaging

- **TSOP Type I & II**
- **LQFP / TQFP (Exposed Pad, Stacked Die)**
- **MQFP (MCM, Stacked Die)**
- **DLP™**

Amkor is Strategically Positioned . . .

- 15 factories in 7 countries
- 24,000 people
- Over 5 million sq. ft. of floor space
- Located in key microelectronic manufacturing centers in Asia
- Sales and service centers worldwide



DLP is a trademark of Texas Instruments

For questions, please e-mail marketing@amkor.com